

## Features /

- Intel 9th Gen. Core i7/i5/i3 Processors / Intel Xeon Processor
- 2 x 260-pin DDR4 (2400MHz) SO-DIMM up to 64GB
- Removable drive-bays for easy data storage maintenance
- Support extensive GPU card expansion for hard-computing requirement

Intel 9th Gen. Core-i and Xeon E Platform Vertical Application System

- Mainboard CPU and GPU card expansion with smart fan support
- Flexible expansion through I/O module with miniPCle and Add-on card



## Specifications / P

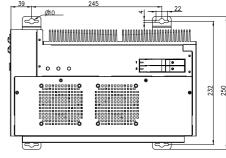
System			
CPU	Intel 9th Gen. Core i7/i5/i3 Processors Intel Xeon Processor		
System Chipset	C246		
Memory	2 x 260-pin DDR4 (2400MHz) SO-DIMM memory sockets, up to 64GB support		
Power	1 x 3-pin terminal block for DC power input 1 x power button with LED light 1 x 2-pin power switch connector		
Default I/O	2 x GbE LAN (RJ-45), LAN1 for PXE Boot-up 4 x USB 3.1 Gen.1 (Type A, with Lock-hole) 2 x USB 2.0 (Type A) 1 x USB 2.0 (Internal Type A in backside for Dongle) 1 x DP 1.2 port 1 x HDMI port 2 x RS-232/422/485 (COM1, COM2, DB9, Default RS-232) 1 x Line-Out, 1 x Mic-In 8 x bits GPIO (4 x in, 4 x out)		

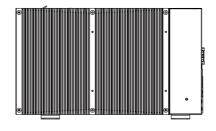
Storage Space	
HDD	2 x 2.5" SATA3 HDD/SSD with removable drive-bays 2 x 2.5" SATA3 HDD/SSD with internal drive-bays

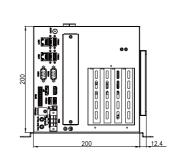
Expansion	
Expansion slot	2 x Full-size miniPCle slots 1 x micro SIM socket PCle Expansion, Power support up to 400W. 1 x PCle-4 in x8 socket (slot #1, GEN.3) 1 x PCle-4 in x8 socket (slot #2, GEN.3) 1 x PCle-16 (slot #3, GEN.3)

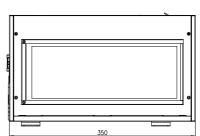
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	Power Input	DC 12~36V (Default 24V)	
	Mechanical		
	Construction	Aluminum Heat-sink. Metal Steel Chassis	
	Mounting	Desktop, Wall Mount	
	Dimensions	200 x 200 x 350 mm Max Add-on Card Size of 308 x 128 mm	
	Net Weight	7 kg	

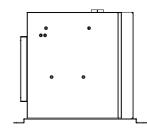


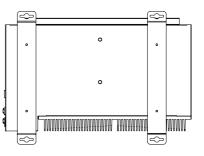












Operating Temperature -20°C~60°C(WT1) with air flow, 0°C to 50°C Fanless Storage Temperature

-40°C~85°C

Storage Humidity 10 to 90%@ 40°C, non-condensing

CE/FCC Class A Certificate

## Operating System Support

Win10 IoT, Linux 4.20.2